

# SOT1445-1

wafer level chip-scale package; 6 bumps; 0.69 x 0.44 x 0.29 mm

12 July 2016

Package information

## 1. Package summary

|  |  |
|--|--|
| <b>Dimensions (mm)</b>                     | 0.69 x 0.44 x 0.29   |
| <b>Terminal position code</b>              | B (bottom)   |
| <b>Package type descriptive code</b>       | WLCSP  |
| <b>Package outline version code</b>        | SOT1445-1  |
| <b>Manufacturer package code</b>           | SOT1445  |
| <b>Package type industry code</b>          | WLCSP6   |
| <b>Package outline version description</b> | wafer level chip-scale package; 6 bumps; 0.69 x 0.44 x 0.29 mm |
| <b>Package style descriptive code</b>      | UC (uncased chip)  |
| <b>Package body material type</b>          | P  |
| <b>Mounting method type</b>                | S (surface mount)  |
| <b>Security status</b>                     | COMPANY PUBLIC   |
| <b>Issue date</b>                          | 11-7-2016  |

Table 1. Package summary

| Symbol         | Parameter                      | Min   | Typ | Nom  | Max   | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| A <sub>2</sub> | package height                 | 0.185 | -   | 0.2  | 0.215 | mm   |
| A              | seated height                  | 0.27  | -   | 0.29 | 0.31  | mm   |
| D              | package length                 | 0.675 | -   | 0.69 | 0.705 | mm   |
| E              | package width                  | 0.425 | -   | 0.44 | 0.455 | mm   |
| e              | nominal pitch                  | -     | -   | 0.25 | -     | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 6    | -     |      |



## 2. Package outline

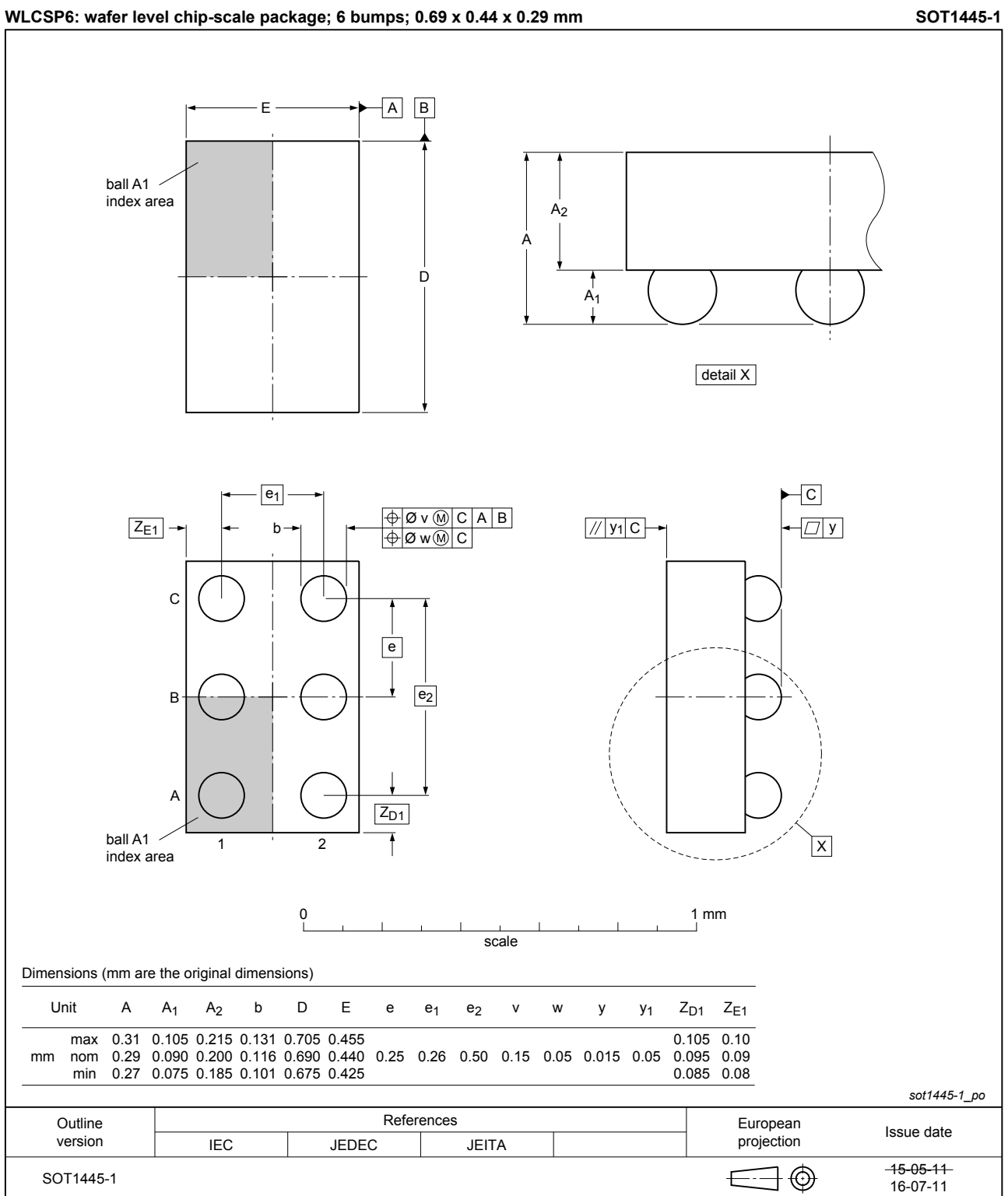


Fig. 1. Package outline WLCSP6 (SOT1445-1)

### 3. Legal information

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